



Material Content Data Sheet



Sales Product Name	TDA21470	Issued	03. June 2021
MA#	MA004242860		
Package	PG-IQFN-39-1	Weight*	112.71 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.538	1.36	1.36	13648	13648
chip_2	inorganic material	silicon	7440-21-3	0.261	0.23	0.23	2320	2320
chip_3	inorganic material	silicon	7440-21-3	0.966	0.86	0.86	8570	8570
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		100	
	non noble metal	zinc	7440-66-6	0.045	0.04		400	
	non noble metal	iron	7439-89-6	0.901	0.80		7995	
	non noble metal	copper	7440-50-8	36.586	32.48	33.33	324611	333106
wire	noble metal	gold	7440-57-5	0.160	0.14	0.14	1420	1420
	organic material	carbon black	1333-86-4	0.081	0.07		721	
	plastics	epoxy resin	-	4.186	3.71		37140	
encapsulation	inorganic material	silicondioxide	60676-86-0	36.373	32.27	36.05	322721	360582
	noble metal	palladium	7440-05-3	0.003			26	
	noble metal	gold	7440-57-5	0.005			41	
	non noble metal	nickel	7440-02-0	0.084	0.07	0.07	748	815
plating	noble metal	gold	7440-57-5	0.008	0.01		69	
	noble metal	palladium	7440-05-3	0.024	0.02		215	
	noble metal	silver	7440-22-4	0.398	0.35		3534	
	non noble metal	nickel	7440-02-0	1.421	1.26	1.64	12604	16422
solder	noble metal	silver	7440-22-4	0.096	0.09		851	
	non noble metal	tin	7440-31-5	0.192	0.17		1703	
	non noble metal	lead	7439-92-1	3.551	3.15	3.41	31504	34058
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.008	0.01		69	
	non noble metal	zinc	7440-66-6	0.031	0.03		275	
	non noble metal	iron	7439-89-6	0.620	0.55		5497	
	non noble metal	copper	7440-50-8	25.158	22.32	22.91	223218	229059
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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